

# Fair-Rite P/N 2506031007H0

## H Chip Bead Material Grade

## Nominal Chemical Composition

Supporting notes:

1. P/N 2506031007H0 consists of:
  - a core H Chip Bead Material Grade
  - b Termination Plating SnNiAg
2. Moisture Sensitivity Level (MSL)= 1
3. Max Reflow Temp= 260 degC
4. Max Time at Max Reflow Temp= 40 sec
5. RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
6. RoHS Conversion Date= 1/1/2005
7. RoHS Compliance Marking is Contained on Shipping Labels

Wt of core (g)=

<u>Ferrite -Compound</u>	<u>CAS Number</u>	<u>wt %</u>	<b>0.0048</b>	
Fe <sub>2</sub> O <sub>3</sub>	1309-37-1	60	0.00288	Compound Weight (g) Breakdown of H Chip Bead Material Grade
NiO	1313-99-1	23	0.00110	
ZnO	1314-13-2	8	0.00038	
CuO	1317-38-0	5	0.00024	
Co <sub>3</sub> O <sub>4</sub>	1308-06-1	3	0.00014	
MnO	1344-43-0	1	0.00005	

Wt of termination (g)=

<u>Termination Plating - Elements</u>	<u>CAS Number</u>	<u>wt %</u>	<b>0.0012</b>	
Sn	7440-31-5	14.3	0.00017	Element Weight (g) Breakdown of Pb- Free Termination Plating
Ni	7440-02-0	6.9	0.00008	
Ag	7440-22-4	78.8	0.00095	

## Calculated Maximum Levels of RoHS Restricted Substances Present in H Chip Bead Material Grade

Wt of core (g)=

<u>Impurity Substance</u>	<u>RoHS Threshold (ppm):</u>	<u>ppm</u>	<b>0.0048</b>	
Cr+6	1000	0.00	0	RoHS Impurity Substance Weight (g) Breakdown of H Chip Bead Material Grade
Cd	100	0.00	0	
Hg	1000	0.00	0	
Pb	1000	0.00	0	
PBB	1000	0.00	0	
PBDE	1000	0.00	0	